

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals

MECHANICAL DATA

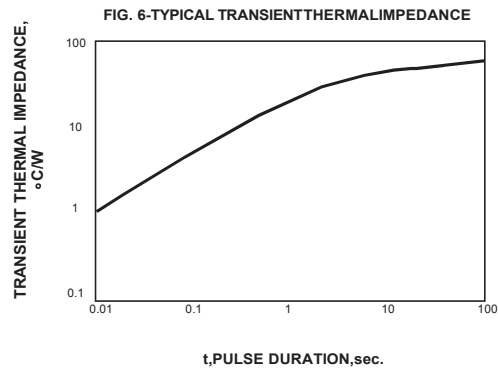
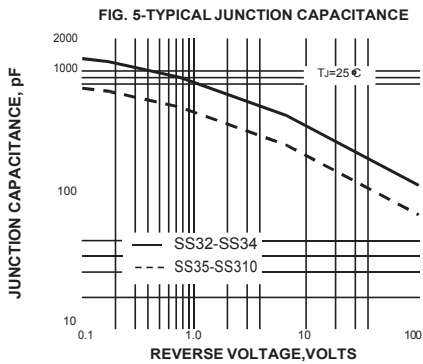
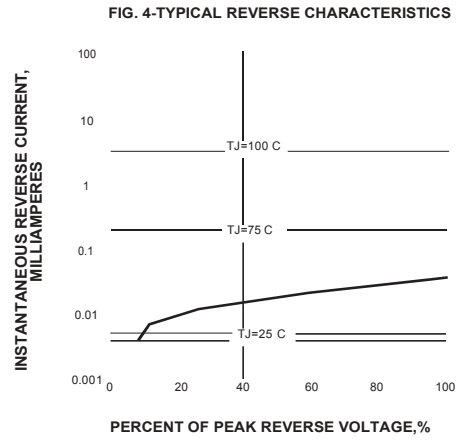
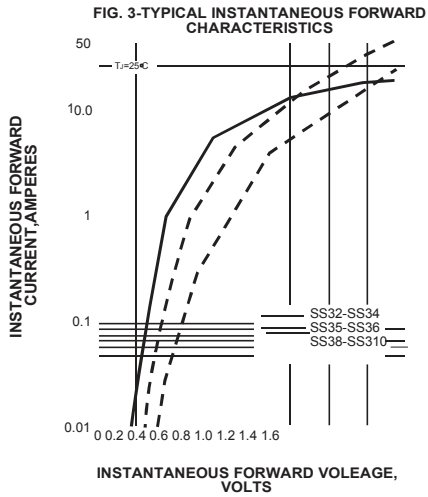
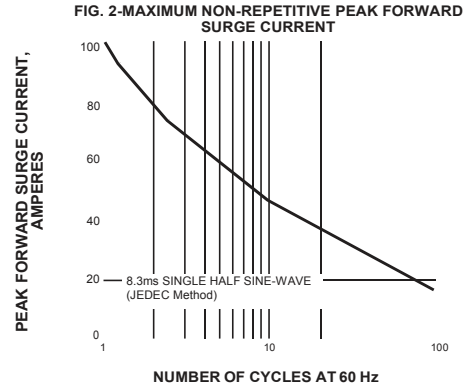
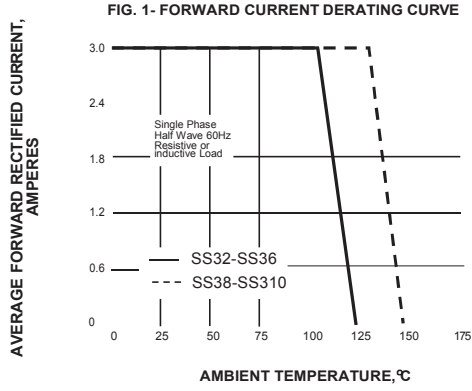
Case: DO-214AC
Terminals: leads solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.002 ounce, 0.07 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

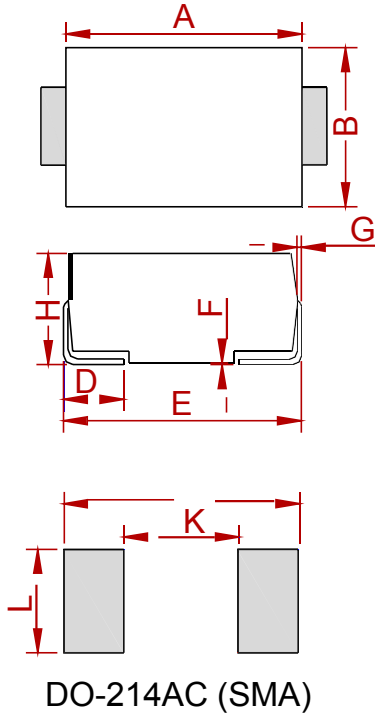
Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS32-MS	SS34-MS	SS36-MS	SS310-MS	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	100	VOLTS
Maximum RMS voltage	V _{RMS}	14	28	42	70	VOLTS
Maximum DC blocking voltage	V _{DC}	20	40	60	100	VOLTS
Maximum average forward rectified current at T _L (see fig. 1)	I _(AV)	3.0				Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	100.0				Amps
Maximum instantaneous forward voltage at 3.0A	V _F	0.55	0.70	0.85		Volts
Maximum DC reverse current at rated DC blocking voltage	I _R	0.5				mA
TA=25°C TA=100°C		20		10		
Typical junction capacitance (NOTE 1)	C _J	500	300			pF
Typical thermal resistance (NOTE 2)	R _{θJA}	55.0				C/W
Operating junction temperature range	T _J	-50 to +125			-50 to +150	°C
Storage temperature range	T _{STG}	-50 to +150				°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS32-MS THRU SS310-MS	SMA	2000

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